

Kulicke & Soffa Industries, Inc.

Kulicke & Soffa and Kinik Sign Collaboration Agreement to Provide Comprehensive Dicing Blades Solutions

SINGAPORE--(BUSINESS WIRE)--Sep. 6, 2017-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company") announced today its collaboration agreement with Kinik Company, to provide comprehensive dicing blades solutions.

This sales and distribution agreement enhances both organizations' complementary product offerings within select markets. Kulicke & Soffa's electro-plated dicing blades target silicon wafer and non-metalized package singulation, while Kinik's molded dicing blades focus on metalized packages and hard-material substrate singulation applications. This initial collaboration partnership establishes a foundation for more meaningful joint development opportunities in the future.

"This is a perfect match for K&S and Kinik to provide customers with a complementary portfolio of dicing blades products," said Eugene Tan, Kulicke & Soffa's Senior Director of Capillary and Blade Business Lines. "We look forward to enhancing this partnership in the future."

William Lee, Kinik's General Manager and Head of Diamond Business Unit said, "This collaboration is an important step in our commitment to better support our customers. Together, with our aligned market-driven strategy, we will provide a broad range of competitive dicing blades solutions to customers."

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices (www.kns.com).

About Kinik

For over 60 years, the Kinik Company (TT: 1560) has been an innovator and leader in diamond and super-abrasive technology. With revenues of over \$145 million, Kinik supplies more than 8,000 customers worldwide with products ranging from all kinds of grinding wheels, hubless dicing blades, polycrystalline diamond (PCD) and polycrystalline boron-nitride (PCBN) precision machining tools to CMP pad conditioners and semiconductor reclaim wafer services. Kinik maintains 4 manufacturing facilities in Taiwan, including the latest state-of-the-art CMP Pad Conditioner Manufacturing Facility in Shulin, with more than 1,600 employees. Kinik is committed to the highest standards Environmental, Health & Safety and is SGS certified for OHSAS 180001, ISO 9001 and 14001 (www.kinik.com.tw).

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